

List of Contents

Chapter 1: Recent Advances in Thin-Film Deposition

Molecular-beam Deposition of High-k Gate Dielectrics for Advanced CMOS	3
<i>A. Dimoulas</i>	
LEPECVD — A Production Technique for SiGe MOSFETs and MODFETs	17
<i>D. Chrastina, B. Rössner, G. Isella, H. von Känel J. P. Hague, T. Hackbarth, H.-J. Herzog, K.-H. Hieber, U. König</i>	
Thin-film Engineering by Atomic-layer Deposition for Ultra-scaled and Novel Devices	31
<i>G. Scarel, M. Fanciulli</i>	
Atomic-layer Deposited Barrier and Seed Layers for Interconnects	39
<i>J. Schuhmacher, A. Martin, A. Satta, K. Maex</i>	
Copper CVD for Conformal Ultrathin-film Deposition	51
<i>M. Joulaud, P. Doppelt</i>	
Pushing PVD to the Limits — Recent Advances	61
<i>Zs. Tókei</i>	

Surface Engineering Using Self-assembled Monolayers: Module Substrates for Atomic-layer Deposition.....	69
<i>C. M. Whelan, A.-C. Demas, A. Romo Negreira, T. Fernandez Landaluce, J. Schuhmacher, L. Carbonell, K. Maex</i>	
Selective Airgaps: Towards a Scalable Low-k Solution	77
<i>J. P. Gueneau de Mussy, G. Beyer, K. Maex</i>	
Silicides — Recent Advances and Prospects	85
<i>J. A. Kittl, A. Lauwers, O. Chamirian, M. A. Pawlak, M. Van Dal, A. Veloso, K. G. Anil, G. Pourtois, M. De Potter, K. Maex</i>	
TEM Characterization of Strained Silicon.....	99
<i>J. P. Morniroli, P. H. Albarède, D. Jacob</i>	
 Chapter 2: Material Aspects of Non-Volatile Memories	
An Introduction to Nonvolatile Memory Technology	111
<i>T. Mikolajick, C.-U. Pinnow</i>	
Floating-dot Memory Transistors on SOI Substrates	127
<i>O. Winkler, M. Baus, M. C. Lemme, R. Rölver, B. Spangenberg, H. Kurz</i>	
Ion-beam Synthesis of Nanocrystals for Multidot	139
Memory Structures	
<i>V. Beyer, J. von Borany</i>	
Scaling of Ferroelectric-based Memory Concepts.....	149
<i>R. Waser</i>	
Device Concepts with Magnetic Tunnel Junctions	163
<i>H. Brückl, J. Bornemeier, A. Niemeyer, K. Rott</i>	
Phase-change Memories.....	177
<i>R. Bez, A. Pirovano, F. Pellizzer</i>	
Amorphous-to-fcc Transition in GeSbTe Alloys.....	189
<i>S. Privitera, C. Bongiorno, E. Rimini, R. Zonca</i>	

Organic Nonvolatile Memories.....	197
<i>Y. Yang, L. Ma, J. Ouyang, J. He, H. M. Liem,</i>	
<i>C.-W. Chu, A. Prakash</i>	

Chapter 3: Materials for Interconnects

Interconnect Technology — Today, Recent Advances and a Look into the Future.....	213
<i>M. Engelhardt, G. Schindler, W. Steinhögl,</i>	
<i>G. Steinlesberger, M. Traving</i>	
Dielectric and Scaling Effects on Electromigration for Cu Interconnects.....	225
<i>P. S. Ho, K.-D. Lee, J. W. Pyun, X. Lu, S. Yoon</i>	
Texture and Stress Study of Sub-Micron Copper Inter- connect Lines using X-ray Micro Diffraction.....	241
<i>I. Zienert, H. Prinz, H. Geisler, E. Zschech</i>	
Stress Modeling for Copper Interconnect Structures	251
<i>V. Sukharev</i>	
Conductivity Enhancement in Metallization Structures of Regular Grains	265
<i>G. D. Knight</i>	
Advanced Barriers for Copper Interconnects.....	283
<i>M. Hecker, R. Hübner, J. Acker, V. Hoffmann,</i>	
<i>N. Mattern, R. Ecke, S. E. Schulz, H. Heuer,</i>	
<i>C. Wenzel, H.-J. Engelmann, E. Zschech</i>	
Synthesis and Characterization of Compounds Obtained by Crosslinking of Polymethyl- hydrosiloxane by Aromatic Rings.....	297
<i>F. Sediri, F. Touati, N. Gharbi</i>	
Revealing the Porous Structure of Low-k Materials through Solvent Diffusion.....	305
<i>D. Shamiryan, M. R. Baklanov, K. Maex</i>	

Carbon Nanotube via Technologies for Future LSI Inteconnects	315
<i>M. Nihei, A. Kawabata, M. Horibe, D. Kondo, S. Sato, Y. Awano</i>	

Nickel Nanowires Obtained by Template Synthesis	327
<i>I. Z. Rahman, K. M. Razeed, M. A. Rahman</i>	

Chapter 4: Materials for Assembly/Packaging

The Importance of Polymers in Wafer-Level Packaging	347
<i>M. Töpper</i>	

Electrically Conductive Adhesives as Solder Alternative: A Feasible Challenge	363
<i>G. Luyckx, G. Dreezen</i>	

The Role of Au/Sn Solder in Packaging	377
<i>H. Oppermann</i>	

Packaging Materials: Organic–Inorganic Hybrids for Millimetre-Wave Optoelectronic	391
<i>N. Rapin</i>	

Wafer-Level Three-Dimensional Hyper-Integration Technology Using Dielectric Adhesive Wafer Bonding	405
<i>J.-Q. Lu, T. S. Cale, R. J. Gutmann</i>	

Chapter 5: Advanced Materials Characterization

Challenges to Advanced Materials Characterization for ULSI Applications	421
<i>A. C. Diebold</i>	

Advanced Material Characterization by TOFSIMS in Microelectronics	437
<i>T. Conard, W. Vandervorst</i>	

Electronic Properties of the Interface Formed by Pr₂O₃ Growth on Si(001), Si(111) and SiC(0001) Surfaces	449
<i>D. Schmeißer, P. Hoffmann, G. Beuckert</i>	
Materials Characterization by Ellipsometry	461
<i>V. G. Polovinkin, M. R. Baklanov</i>	
Thermal Desorption Spectrometry as a Method of Analysis for Advanced Interconnect Materials	475
<i>L. Carbonell, A. M. Hoyas, C. M. Whelan, G. Vereecke</i>	
Electron Backscatter Diffraction: Application to Cu Interconnects in Top-View and Cross Section	485
<i>M. A. Meyer, I. Zienert, E. Zschech</i>	
X-ray Reflectivity Characterisation of Thin-Film and Multilayer Structures	497
<i>P. Zaumseil</i>	

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